



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Luetzen, *et al.* Docket No.: INF115
Serial No.: 10/721,225 Art Unit: 1763
Filed: November 26, 2003 Examiner: George A. Goudreau
For: Method and Structures for Increasing the Structure Density and the Storage Capacitance in a Semiconductor Wafer

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Respectfully submitted,

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